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OMB No. 0651-0011 (Exp. 4/94)

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U.S. DEPARTMENT OF COMMERCE
Patent and Trademark Office

To the honorable Commissioner of Patents and Trademarks: Please record the attached original documents or copy thereof.

1. Name of conveying party(ies):

WJ SEMICONDUCTOR EQUIPMENT GROUP, INC.

Additional name(s) of conveying party(ies) attached? ☐ Yes ☒ No

3. Nature of Conveyance:

☒ Assignment

☐ Merger

☐ Security Agreement

☐ Change of Name

☐ Other:

Execution Date: March 29, 1999

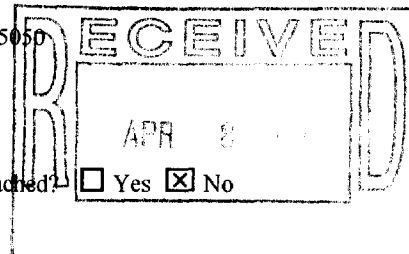
2. Name and address of receiving party(ies):

APPLIED MATERIALS, INC.

2881 Scott Blvd.

Santa Clara, CA 95050

Additional name(s) attached? ☐ Yes ☒ No



4. Application number(s) or patent number(s)

If this document is being filed together with a new application, the execution date of the application is:

A. Patent Application No.(s)

08/804,212

08/868,041

09/092,565

08/971,316

08/865,330

09/075,854

09/152,849

B. Patent No.(s)

Additional numbers attached? ☐ Yes ☒ No

5. Name and address of party to whom correspondence concerning document should be mailed:

Willis E. Higgins

Cooley Godward LLP

Five Palo Alto Square

3000 El Camino Real

Palo Alto, CA 94306

6. Total number of application and patents involved: 7

7. Total Fee (37 CFR 3.41).....\$280.00

☒ Enclosed

☐ Authorized to be charged to deposit account

8. Deposit account number: 03-3117

(Attach duplicate copy of this page if paying by deposit account)

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9. Statement and signature.

To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.

Reg. No.: 23,025

Name of Person Signing: Willis E. Higgins

Signature: Willis E. Higgins

Date: 4-7-99

Total number of pages including cover sheet, attachments, and document: 2

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Date of Deposit: April 7, 1999

I hereby certify that this paper or fee is being deposited with the United States Postal Service "Express Mail Post Office to Addressee" service under 37 CFR 1.10 on the date indicated above and is addressed to the Honorable Commissioner of Patents and Trademarks, Box Assignments, Washington, D.C. 20231.

Date: April 7, 1999 By: Christine Mancheser

Christine Mancheser

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PATENT

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SCHEDULE A TO PATENT APPLICATION ASSIGNMENT

SEG Division	Reference No.			Title/Inventors	Serial No./ Filing Date	Patent No./ Issue Date	Foreign Countries
	FA	60785	KR				
HDP			AJT MSS	METHOD OF FORMING A FLUORINATED SILICON OXIDE LAYER USING PLASMA CHEMICAL VAPOR DEPOSITION; Qian, Schmidt, Nobinger	705764/96 02/05/96		Korea
HDP	FA	60785	JP	METHOD OF FORMING A FLUORINATED SILICON OXIDE LAYER USING PLASMA CHEMICAL VAPOR DEPOSITION; Qian, Schmidt, Nobinger	8-524377 02/05/96		Japan
HDP	FE	60785	EP	METHOD OF FORMING A FLUORINATED SILICON OXIDE LAYER USING PLASMA CHEMICAL VAPOR DEPOSITION; Qian, Schmidt, Nobinger	96906308.0 02/05/96		Europe
HDP	FP	60785	PC	METHOD OF FORMING A FLUORINATED SILICON OXIDE LAYER USING PLASMA CHEMICAL VAPOR DEPOSITION; Qian, Schmidt, Nobinger	PCT/US96/01589 02/05/96	Closed *	PCT
HDP	FA	62195	SG	ELECTROSTATIC CHUCK ASSEMBLY; Van Os	9801226-3 06/21/96		Singapore
HDP	FA	62195	KR	ELECTROSTATIC CHUCK ASSEMBLY; Van Os	27699/96 07/10/96		Korea
HDP	FA	62195	JP	ELECTROSTATIC CHUCK ASSEMBLY; Van Os	8-179134 07/09/96		Japan
HDP	FA	62195	CN	ELECTROSTATIC CHUCK ASSEMBLY; Van Os	96196450.2 06/21/96		China
HDP	FE	62195	EP	ELECTROSTATIC CHUCK ASSEMBLY; Van Os	96921754.6 06/21/96		Europe

SEG Division	Reference No.			Title/Inventors	Serial No./ Filing Date	Patent No./ Issue Date	Foreign Countries
	FP	62195	PC				
HDP				ELECTROSTATIC CHUCK ASSEMBLY; Ross, Van Os	PCT/US96/10739 06/21/96	Closed *	PCT
HDP	A	62196		GAS DISTRIBUTION RING; Nitescu	08/499,861 07/10/95	Abandoned *	
HDP	FP	62196	PC	GAS DISTRIBUTION APPARATUS; Nitescu, Matthiesen	PCT/US96/10657 06/21/96	Abandoned *	PCT
HDP	A	62268		A PLASMA-ENHANCED PROCESSING REACTOR AND METHOD; VanOs	08/500,493 07/10/95	Abandoned in favor of FWC 08/804,212 (A-62268-2)	
HDP	FA	62268	SG	A PLASMA-ENHANCED PROCESSING REACTOR AND METHOD; VanOs	9705412-6 06/21/96		Singapore
HDP	FA	62268	KR	PLASMA-ENHANCED CHEMICAL PROCESSING REACTOR AND METHOD; VanOs	27700/96 07/10/96		Korea
HDP	FA	62268	JP	PLASMA ENHANCED CHEMICAL PROCESSING REACTOR AND METHOD; VanOs	8-180459 07/10/96		Japan
HDP	FA	62268	CN	A PLASMA-ENHANCED PROCESSING REACTOR AND METHOD; VanOs	96195202.4 06/21/96		China
HDP	FE	62268	HK	A PLASMA-ENHANCED PROCESSING REACTOR AND METHOD; VanOs	98109046.8 07/10/98		Hong Kong
HDP	FE	62268	EP	A PLASMA-ENHANCED PROCESSING REACTOR AND METHOD; VanOs	96922534.1		Europe
HDP	FP	62268	PC	A PLASMA-ENHANCED CHEMICAL PROCESSING REACTOR AND METHOD; Fenske, Ross, Matthiesen, VanOs, Durbin	PCT/US96/10705 06/21/96	Closed *	PCT
HDP	A	62268	1	PLASMA ENHANCED CHEMICAL PROCESSING REACTOR AND METHOD; VanOs	08/804,212 02/21/97 Div. of 08/500,493 Filed 07/10/95		

SEG Division	Reference No.			Title/Inventors	Serial No./ Filing Date	Patent No./ Issue Date	Foreign Countries
	A	62268	3				
HDP	A			PLASMA ENHANCED CHEMICAL PROCESSING REACTOR AND METHOD; VanOs	09/092,565 06/05/98 Con't of 08/909,580, which is a FWC of 08/500,493		
HDP	A	62403		GAS INJECTION SYSTEM FOR SEMICONDUCTOR PROCESSING; Young	08/546,885 10/23/95	Abandoned in favor of FWC 08/928,747 (A-62403-1)	
HDP	FA	62403	KR	GAS INJECTION SYSTEM FOR SEMICONDUCTOR PROCESSING; Young	702927/98 10/18/96		
HDP	FA	62403	SG	GAS INJECTION SYSTEM FOR SEMICONDUCTOR PROCESSING; Young	9802390-6 10/18/96		
HDP	FA	62403	TW	GAS INJECTION SYSTEM FOR SEMICONDUCTOR PROCESSING; Young	84111113 10/20/95		Taiwan
HDP	FA	62403	JP	GAS INJECTION SYSTEM FOR SEMICONDUCTOR PROCESSING; Young	9-516663 10/18/96		
HDP	FA	62403	CN	GAS INJECTION SYSTEM FOR SEMICONDUCTOR PROCESSING; Young	96197800-7 10/18/96		
HDP	FE	62403	EP	GAS INJECTION SYSTEM FOR SEMICONDUCTOR PROCESSING; Young	96936631.9 10/18/96		
HDP	FP	62403	PC	GAS INJECTION SYSTEM FOR SEMICONDUCTOR PROCESSING; Young	PCT/US96/16647 10/18/96	Closed *	PCT
HDP	A	63657		METHOD AND APPARATUS FOR CLAMPING A SUBSTRATE; Graven, Ra, Schmidt	08/865,330 05/29/97		
HDP	FA	63657	TW	METHOD AND APPARATUS FOR CLAMPING A SUBSTRATE; Graven, Ra, Schmidt	87106526 04/28/98		Taiwan

PATENT
REEL: 9887 FRAME: 0356

SEG Division	Reference No.			Title/Inventors	Serial No./ Filing Date	Patent No./ Issue Date	Foreign Countries
	FP	63657	PC				
HDP				METHOD AND APPARATUS FOR CLAMPING A SUBSTRATE; Graven, Ra, Schmidt	PCT/US98/09573 05/11/98		PCT
HDP	A	63671		WAFER PROCESSING REACTOR SYSTEM WITH PROGRAMMABLE PROCESSING PARAMETERS AND METHOD; Putnam-Pite, et al.	09/152,849 09/14/98		
HDP	A	64011		ELECTROSTATIC CHUCK WITH INTEGRATED GUARD RING; Park	08/868,041 06/03/97		
HDP	FA	64011	TW	ELECTROSTATIC CHUCK WITH INTEGRATED GUARD RING; Park	87107318 05/12/98		Taiwan
HDP	FP	64011	PC	ELECTROSTATIC CHUCK WITH INTEGRATED GUARD RING; Park	PCT/US98/11227 06/01/98		PCT
HDP	A	64333		PLASMA ENHANCEMENT BY COMBINING CAPACITIVE AND INDUCTIVE COUPLING; Pacak	08/971,316 11/17/97		
HDP	FA	64333	TW	PLASMA ENHANCEMENT BY COMBINING CAPACITIVE AND INDUCTIVE COUPLING; Pacak	87116453 10/02/98		Taiwan
HDP	FP	64333	PC	PLASMA ENHANCEMENT BY COMBINING CAPACITIVE AND INDUCTIVE COUPLING; Pacak	PCT/US98/24574 11/17/98		PCT
HDP	A	65297		GLOBAL PLANARIZATION TECHNIQUES FOR SEMICONDUCTOR DEVICES USING HIGH DENSITY PLASMA SYSTEMS; ABRAHAM	09/075,854 05/11/98		

SEG Division	Reference No.			Title/Inventors	Serial No./ Filing Date	Patent No./ Issue Date	Foreign Countries
	FP	65297	PC				
HDP				GLOBAL PLANARIZATION TECHNIQUES FOR SEMICONDUCTOR DEVICES USING HIGH DENSITY PLASMA SYSTEMS; ABRAHAM	PCT/US99/05551 03/15/99		PCT
HDP	FA	65297	TW	GLOBAL PLANARIZATION TECHNIQUES FOR SEMICONDUCTOR DEVICES USING HIGH DENSITY PLASMA SYSTEMS; ABRAHAM			Taiwan

* denotes files that have been abandoned and/or closed and are not subject to the representations and warranties in Article 2 of the Asset Purchase Agreement.

PATENT ASSIGNMENT

WHEREAS, WJ SEMICONDUCTOR EQUIPMENT GROUP, INC., a California corporation having offices at 3333 Hillview Avenue, Palo Alto, CA 94304 ("SELLER"), owns, by assignment, all right, title, and interest in and to those United States and foreign patent applications listed on **Schedule A**, attached hereto and incorporated herein (collectively, the "Patents"); and

WHEREAS, APPLIED MATERIALS, INC., a Delaware corporation having offices at 2881 Scott Blvd., Santa Clara, CA 95050 ("PURCHASER"), desires to own SELLER'S entire right, title, and interest in and to the Patents.

NOW THEREFORE, be it known that, for good and valuable consideration, receipt of which is hereby acknowledged, SELLER hereby sells, assigns, transfers, and sets over to PURCHASER, its lawful successors and assigns, SELLER'S entire right, title, and interest in and to the Patents, the inventions claimed therein, and all patents that may be granted thereon, and all divisions, continuations, reissues, and extensions thereof, together with all claims for damages by reason of past infringement thereof, with the right to sue for, and collect the same for PURCHASER'S own benefit.

This Assignment is subject to and governed by the Asset Purchase Agreement between SELLER, PURCHASER, and WATKINS-JOHNSON COMPANY ("PARENT") of even date herewith (the "Purchase Agreement"). Nothing in this Assignment is intended to (a) provide any rights to PURCHASER, PARENT or SELLER beyond those rights expressly provided to the PURCHASER, PARENT or SELLER in the Purchase Agreement, (b) impose any obligations or liabilities on PURCHASER, PARENT or SELLER beyond those obligations and liabilities expressly imposed on PURCHASER, PARENT or SELLER in the Purchase Agreement, or (c) limit any of the rights or remedies available to the PURCHASER, PARENT or SELLER under the Purchase Agreement.

IN TESTIMONY WHEREOF, SELLER has caused its authorized representative to execute this Assignment.

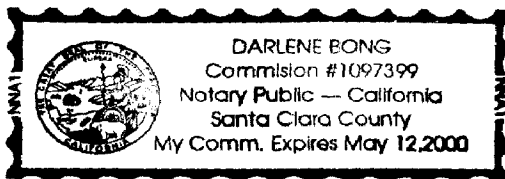
WJ SEMICONDUCTOR EQUIPMENT GROUP, INC.

By: Scott Buchanan

Title: SCOTT BUCHANAN

Date: 3-29-99

On this 20th day of March, 1999, before me appeared Scott Buchanan, the person who signed this instrument on behalf of WJ SEMICONDUCTOR EQUIPMENT GROUP, INC. who acknowledged that he/she signed it on behalf of the identified corporation as Vice President, of the identified corporation and pursuant to the authority duly received. CFO & Treasurer



Darlene Bong
Notary Public

376814 v2/PA

RECORDED: 04/08/1999

PATENT
REEL: 9887 FRAME: 0359